

In the Specification:

After the last page of the received specification, please add the following Abstract, a copy of which is attached to this Amendment on a separate sheet in accordance with the Examiner's request,.

An electronic package assembly includes a number of semiconductor devices with first and second sides. A printed circuit substrate has a number of printed circuit patterns bonded to conductive pads of the first sides of the devices. A metal leadframe includes leads which provide external connections for the package assembly, and also includes a non-lead island portion bonded to conductive pads of the second sides of the devices. In this way the island portion of the leadframe forms an interconnection between the second sides of the devices.